

NC259FPA ULTRAFINE NO CLEAN SOLDER PASTE

FEATURE

- Precise print definition with Type 6 and smaller alloy powder
- Excellent wetting/high shear strength
- Clear flux residue
- Nitrogen reflow recommended
- Zero halogen
- 8-hour stencil life

DESCRIPTION

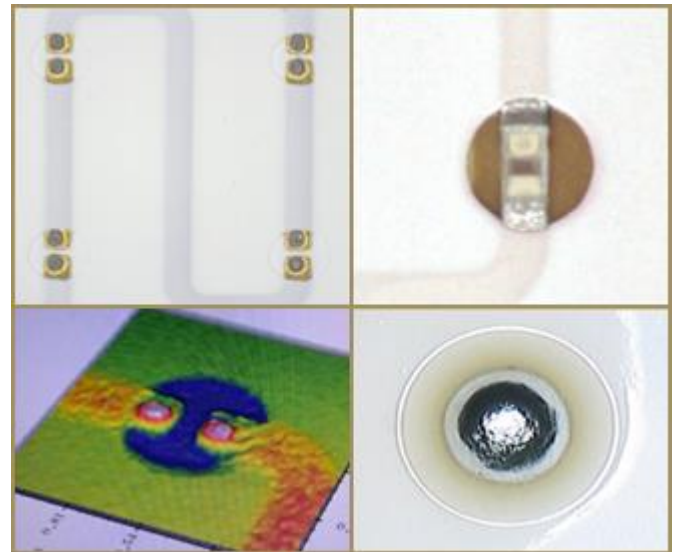
AIM's NC259FPA Ultrafine No Clean Solder Paste has been developed for use with Type 6 and finer solder powder. NC259FPA demonstrates high transfer efficiency and precise print definition. The NC259FPA activator system promotes wetting on all surface finishes resulting in shear values up to 150 gf. NC259FPA residue has high SIR values and is water clear. NC259FPA provides high tack force required for mass transfer assembly.

HANDLING & STORAGE

PARAMETER	TIME	TEMPERATURE
Refrigerated shelf life	6 months	0°C - 12°C (32°F - 55°F)
Unrefrigerated sealed shelf life	2 weeks	< 25°C (< 77°F)

NC259FPA should be consumed within 24 hours after packaging seal is broken. Paste may remain on the printer for 6-8 hours. Do not add used paste to unused paste. Store used paste separately; keep unused paste tightly sealed with internal plug or end cap in place. Please refer to NC259FPA Certificate of Analysis for product specific information. Additional handling recommendations can be found at:

https://aimsolder.com/sites/default/files/aim_paste_handling_guideline_revnf1.pdf.



CLEANING

Pre-reflow: AIM DJAW-10 effectively removes NC259FPA from stencils while in process. DJAW-10 can be hand applied or used in under-stencil wipe equipment. DJAW-10 will not dry NC259FPA and will enhance transfer properties. Do not over-apply DJAW-10. Do not apply DJAW-10 to stencil topside. Isopropanol (IPA) is not recommended in process but may be used as a final stencil rinse.

Post-reflow flux residue: NC259FPA residues can remain on the assembly after reflow and do not require cleaning. Where cleaning is mandated, AIM has worked closely with industry partners to ensure that NC259FPA residues can be effectively removed with common defluxing agents. Contact AIM for cleaning compatibility information.

REFLOW PROFILE

Detailed profile information may be found at <http://www.aimsolder.com/reflow-profile-supplements>. Contact AIM for additional information.

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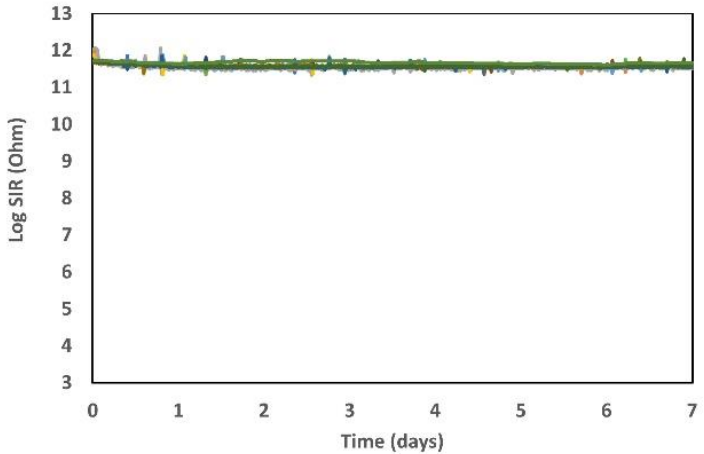
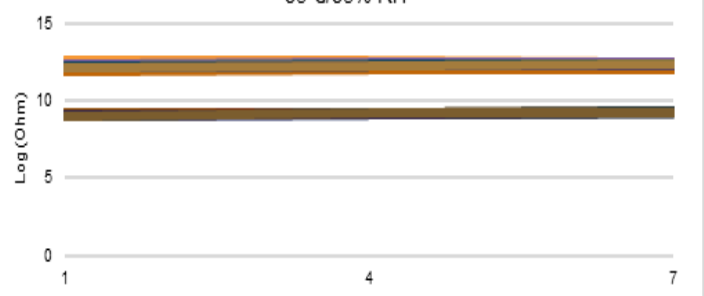
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TEST DATA SUMMARY

NAME	TEST METHOD	RESULTS	
IPC Flux Classification	J-STD-004 A, B, C 3.3	ROLO	
NAME	TEST METHOD	TYPICAL RESULTS	IMAGE
Copper Mirror	J-STD-004C 3.3.1.1 IPC-TM-650 2.3.32	No breakthrough Low	
Corrosion	J-STD-004C 3.3.1.2 IPC-TM-650 2.6.15	No corrosion Low	<p>After 10 days incubation</p> 
Quantitative Halides	J-STD-004C 3.3.1.3 IPC-TM-650 2.3.28.1	<0.05% Low	
Qualitative Halides, Silver Chromate	J-STD-004C 3.4.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004C 3.4.1.2 IPC-TM-650 2.3.35.1	PASS	
Halogen Content	EN 14582	PASS	Halogen-free

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NAME	TEST METHOD	TYPICAL RESULTS	IMAGE
Surface Insulation Resistance	J-STD-004 Current Rev. IPC-TM-650 2.6.3.7	No-clean state \geq 100 M Ω Low	<p style="text-align: center;">40°C/ 90%RH</p> 
Surface Insulation Resistance	J-STD-004 Current Rev. IPC-TM-650 2.6.3.3	No-clean state \geq 100 M Ω Low	<p style="text-align: center;">85°C/85% RH</p> 
Flux Solids, Nonvolatile Determination	J-STD-004C 3.3.2.1 IPC-TM-650 2.3.34	74% solids content	
Acid Value	J-STD-004 Current Rev. TM-650 2.3.13	174.2 mg KOH /g	
Viscosity (Malcom)	J-STD-005A 3.5.1 IPC-TM-650 2.4.34	170-210 PaS* Typical	*Formula-dependent
Visual	J-STD-004C 3.3.2.5	PASS	
Slump	J-STD-005A 3.6 IPC-TM-650 2.4.35	PASS	
Tack Force	JIS standard Z 3284	120 gf Typical	*Formula-dependent

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